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**Nomura et al.**

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(54) **MODULE AND METHOD OF  
MANUFACTURING THE SAME**

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(2013.01); **H05K 2201/10378** (2013.01); **H05K**  
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**2203/1327** (2013.01); **Y10T 29/49146**  
(2015.01)

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H05K 2201/2036; H05K 1/144; H05K  
2201/041–2201/042  
USPC ..... 361/760–790; 257/685–688  
See application file for complete search history.

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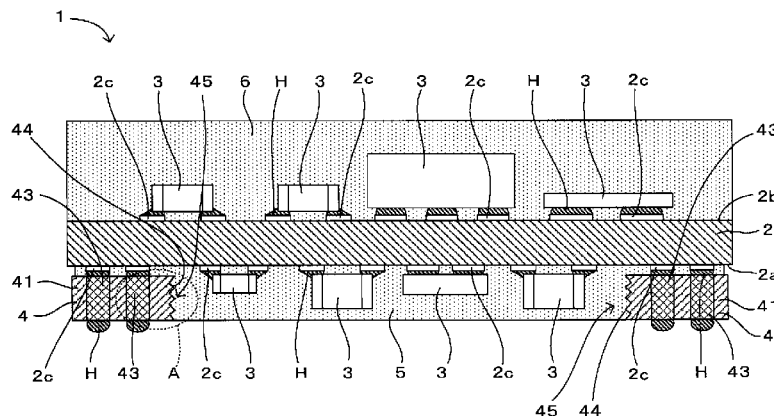
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(57) **ABSTRACT**

An engagement structure for preventing the separation of a  
resin layer is formed in a contact surface of an insulating  
substrate in a connecting component, the contact surface  
being in contact with the resin layer. The resin layer engages  
with the engagement structure in the contact surface in the  
insulating substrate in contact with the resin layer, the  
contact surface forming the side surface of the connecting  
component.

**12 Claims, 14 Drawing Sheets**



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H05K 1/03 (2006.01) 439/65  
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FIG. 1

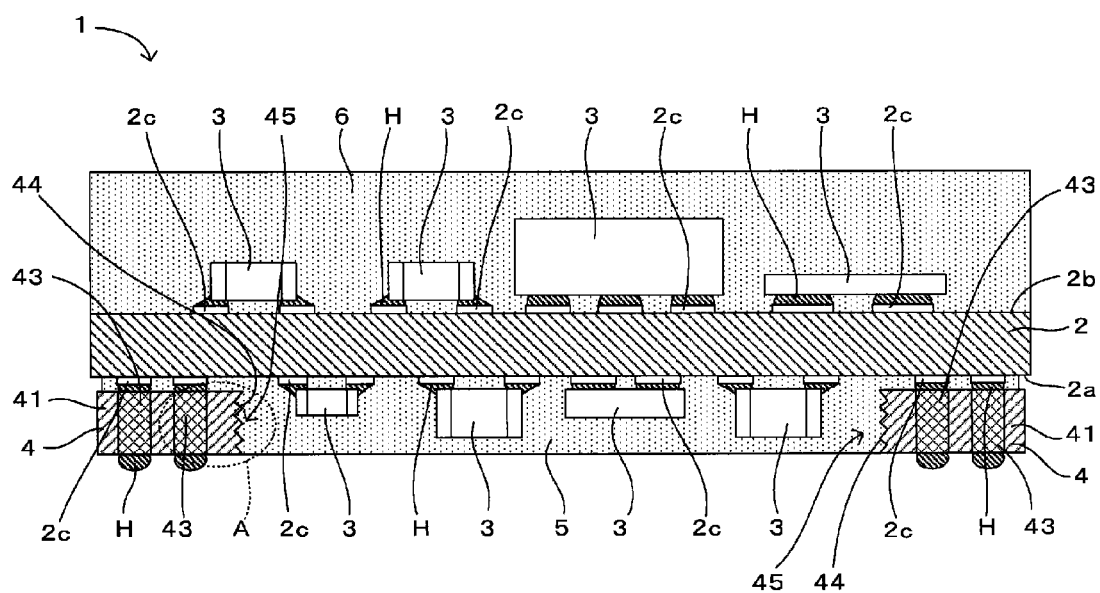


FIG. 2

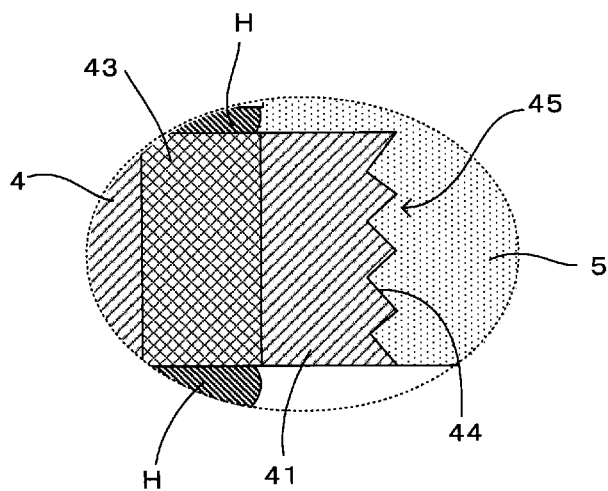


FIG. 3

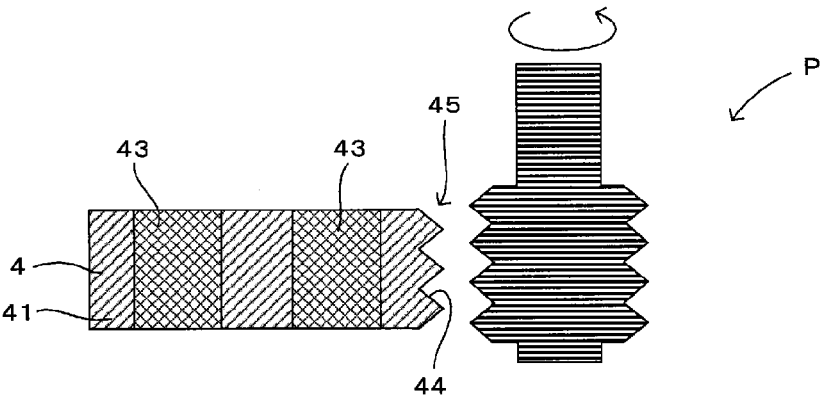


FIG. 4

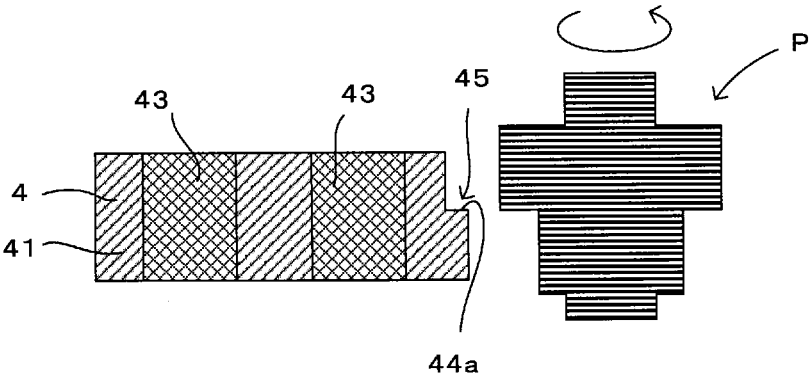


FIG. 5

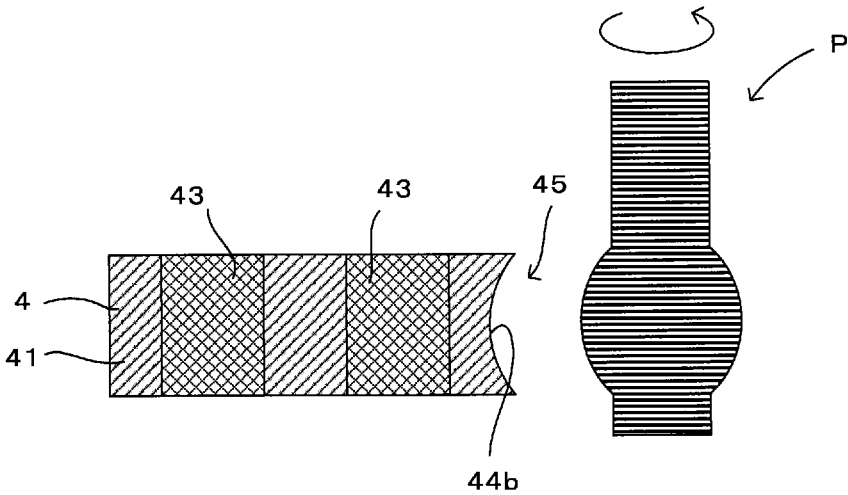


FIG. 6

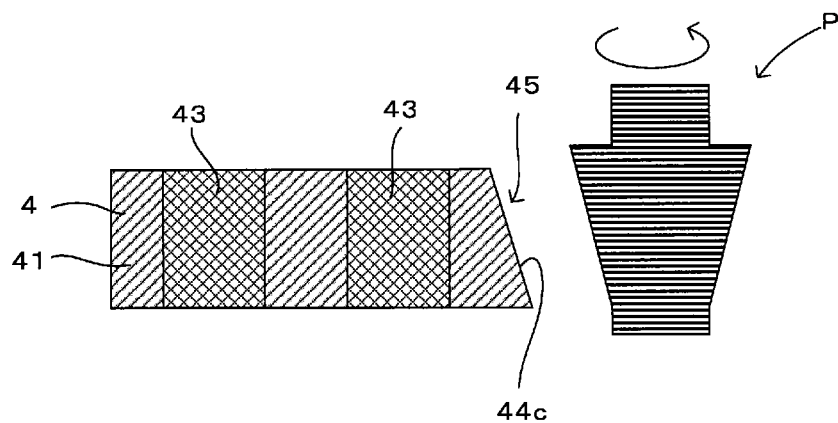
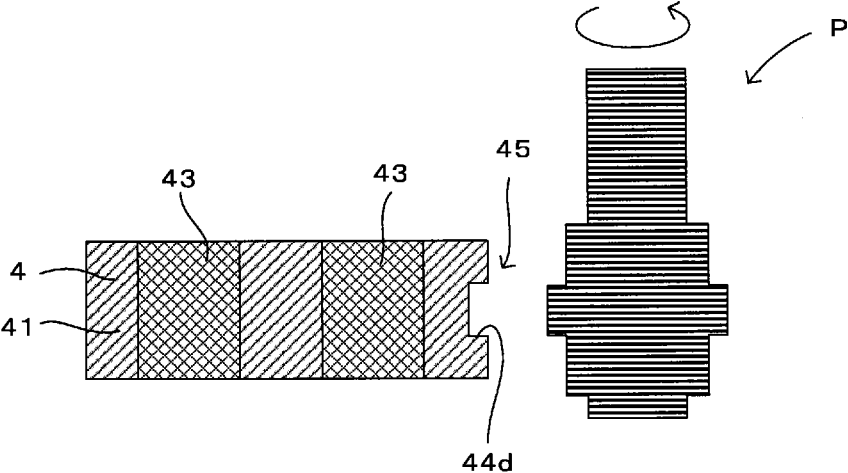




FIG. 7



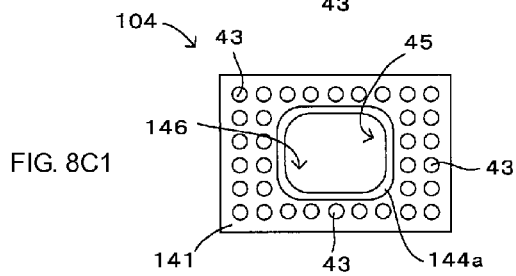
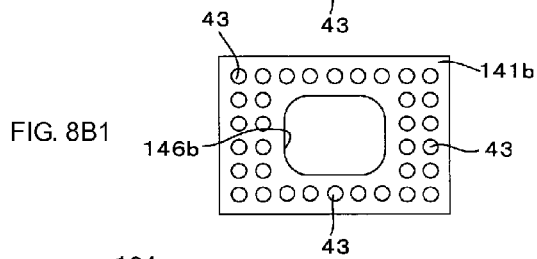
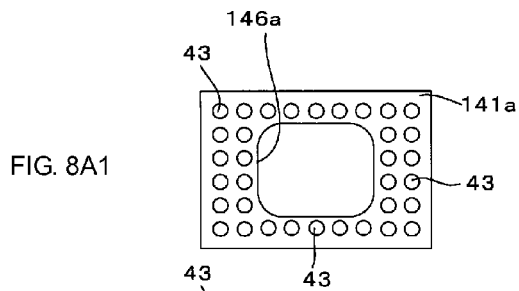


FIG. 8A2

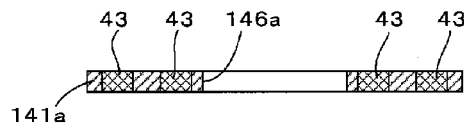


FIG. 8B2

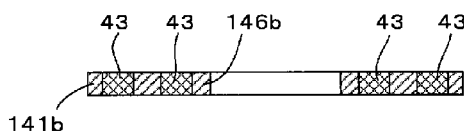
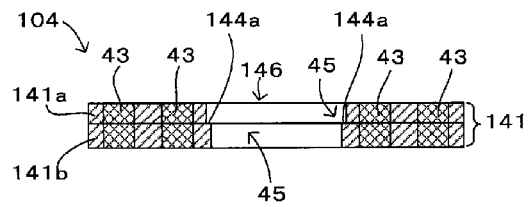


FIG. 8C2



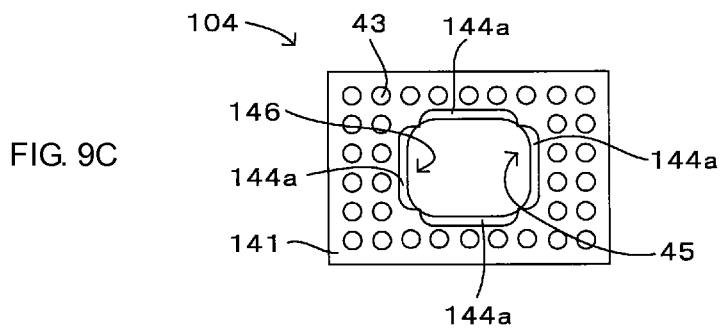
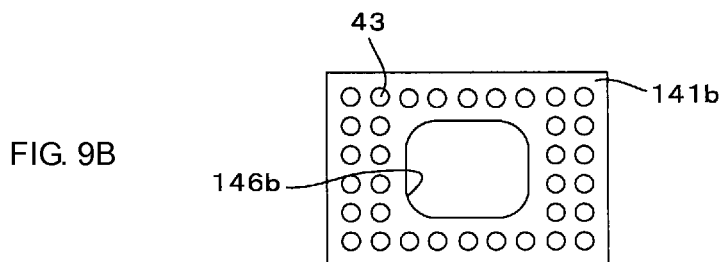
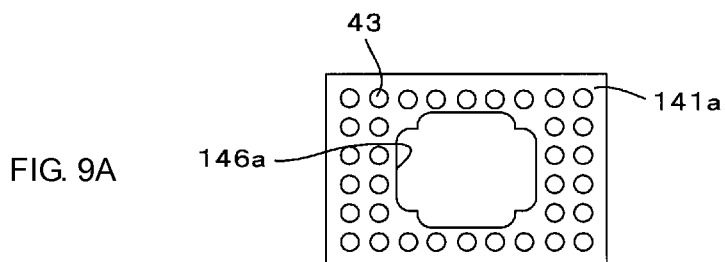


FIG. 10A

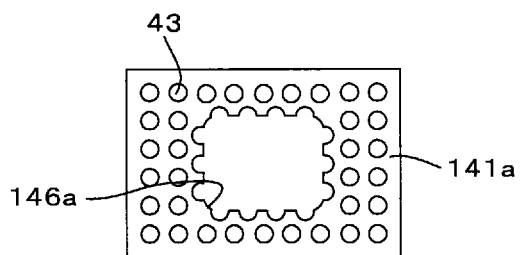


FIG. 10B

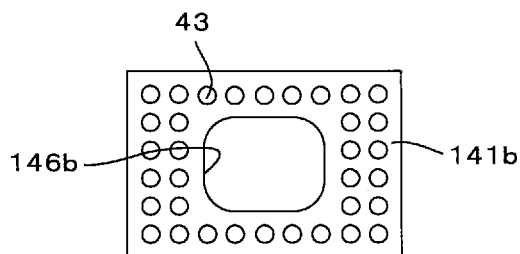


FIG. 10C

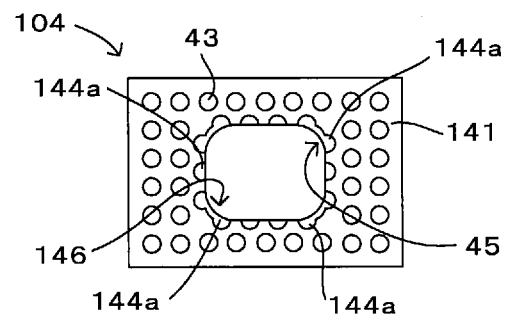


FIG. 11A

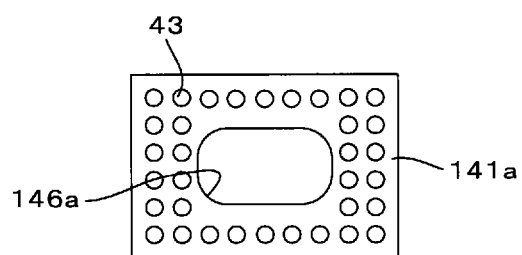


FIG. 11B

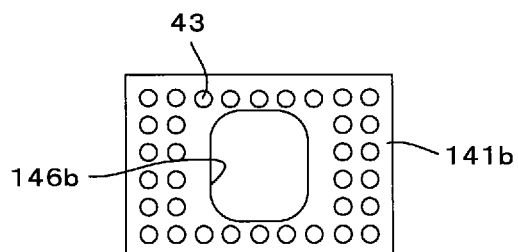


FIG. 11C

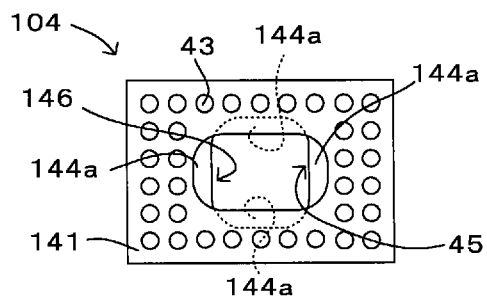


FIG. 12A

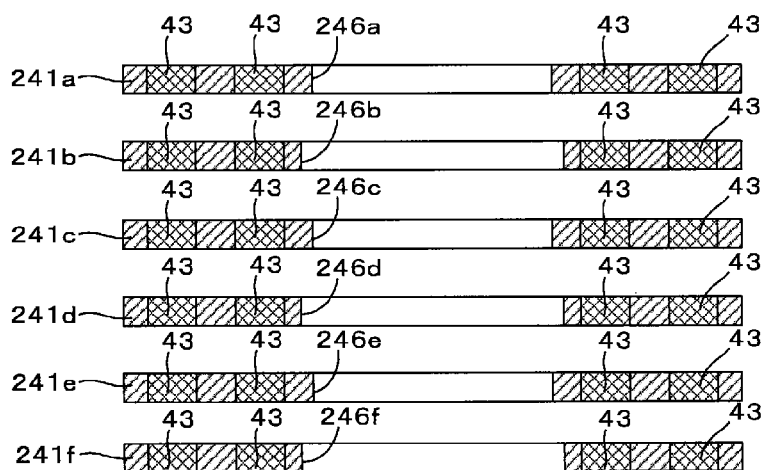


FIG. 12B

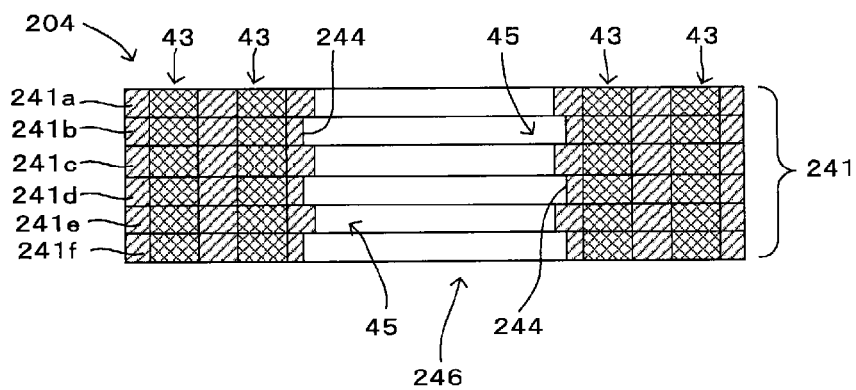


FIG. 13A

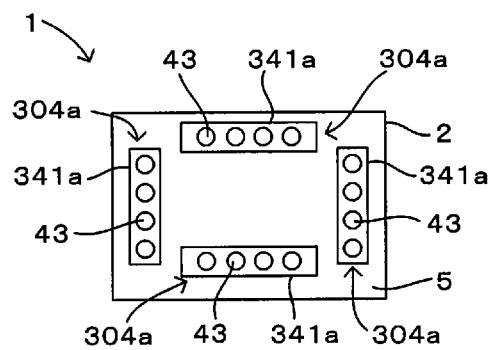


FIG. 13B

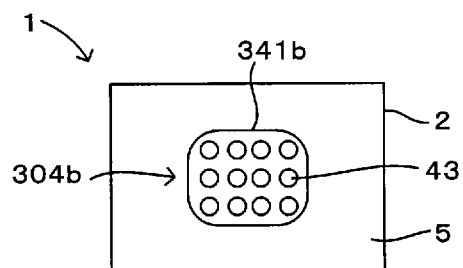
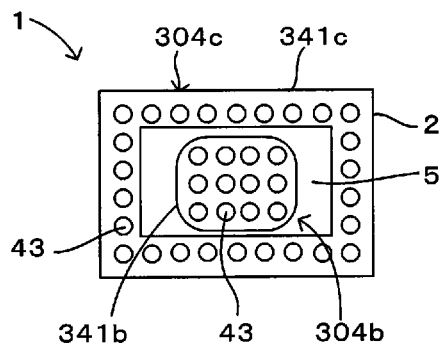
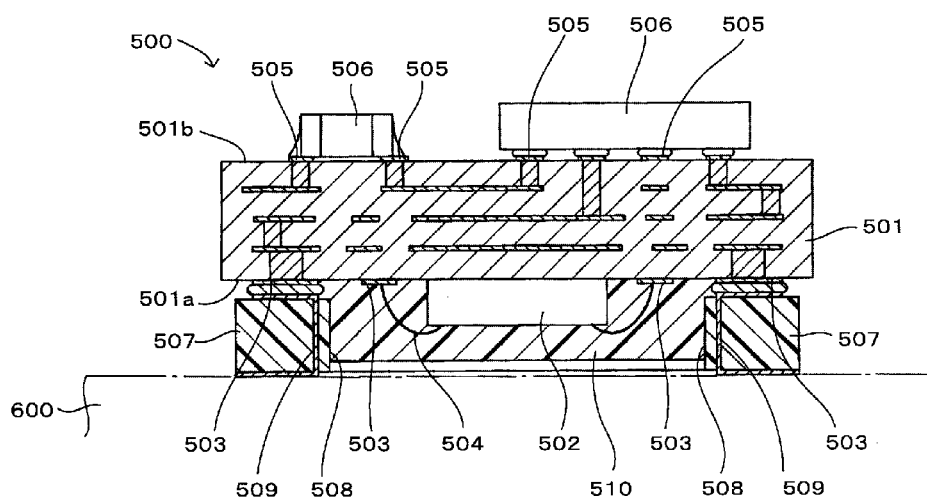


FIG. 13C



PRIOR ART

FIG. 14





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## MODULE AND METHOD OF MANUFACTURING THE SAME

### BACKGROUND OF THE INVENTION

#### 1. Field of the Invention

The present invention relates to a module including a resin layer on a first principal surface of a circuit board and a method of manufacturing the module.

#### 2. Description of the Related Art

In a known module **500** illustrated in FIG. **14**, a mounting component **502**, such as an IC chip, is mounted on a first principal surface **501a** of a circuit board **501**, and the mounting component **502** and mounting electrodes **503** on the first principal surface **501a** of the circuit board **501** are connected to each other with bonding wires **504**. Mounting components **506**, such as chip capacitors or IC chips, are mounted on mounting electrodes **505** on a second principal surface **501b** of the circuit board **501** by solder reflowing or flip-chip bonding as needed.

A connecting component **507** for use in external connection for connecting the circuit board **501** to another board **600** or other element is mounted on the mounting electrodes **503** on the first principal surface **501a** of the circuit board **501** using binders, such as solder. The connecting component **507** has a frame shape with a through-hole **508** in its substantially central portion. The mounting component **502** is arranged in a cavity formed from the through-hole **508**. The circuit board **501** and the board **600** are electrically connected to each other with a connection member **509** on the connecting component **507**. To protect the mounting component **502** from mechanical breakage and the environment, such as heat or moisture, a resin layer **510** formed by filling the cavity formed from the through-hole **508** with a resin is disposed so as to cover the first principal surface **501a** of the circuit board **501**, the mounting component **502**, and the inner side surface of the connecting component **507** (see, for example, paragraph Nos. 0051 to 0058 and FIG. 1 in International Publication No. 2007/110985).

The above-described known module **500** has a low degree of adhesion between the inner side surface of the connecting component **507** and the resin layer **510**. Thus the inner side surface and the resin layer **510** may be detached from each other, the resin layer **510** or the connecting component **507** may be separated from the first principal surface **501a** of the circuit board **501**. This may lead to degradation in module characteristics.

### BRIEF SUMMARY OF THE INVENTION

Accordingly, it is an object of the present invention to provide a technique capable of stabilizing module characteristics by preventing the separation of a resin layer or a connecting component on a first principal surface of a circuit board.

According to preferred embodiments of the present invention, a module includes a circuit board, a mounting component, a connecting component, and a resin layer. The mounting component is mounted on a first principal surface of the circuit board. The connecting component for use in external connection is mounted on the first principal surface of the circuit board. The resin layer covers the first principal surface of the circuit board, the mounting component, and a side surface of the connecting component. The connecting component includes an insulating substrate and a plurality of interlayer connection conductors arranged in the insulating substrate. Each of the interlayer connection conductors

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includes a first end connected to the first principal surface of the circuit board and a second end externally connected. An engagement structure for preventing the resin layer from being separated is formed in a contact surface of the insulating substrate with the resin layer.

In the above-described module, the mounting component and the connecting component for use in external connection are mounted on the first principal surface of the circuit board. The resin layer covering the first principal surface of the circuit board, the mounting component, and the side surface of the connecting component is disposed on the first principal surface of the circuit board. The interlayer connection conductors are disposed in the insulating substrate in the connecting component. Each of the interlayer connection conductors includes the first end connected to the first principal surface of the circuit board and the second end externally connected. Thus the circuit board is externally connected through the interlayer connection conductors.

The engagement structure for preventing the separation of the resin layer is disposed in the contact surface of the insulating substrate in the connecting component in contact with the resin layer. Accordingly, the engagement of the resin layer with the engagement structure formed in the contact surface of the insulating substrate forming the side surface of the connecting component in contact with the resin layer can prevent the separation of the resin layer or the connecting component on the first principal surface of the circuit board. The separation of the resin layer from the side surface of the connecting component can also be prevented. The degree of adhesion in the contact surface between the resin layer and the connecting component can be improved. Thus the module characteristics can be stabilized.

The insulating substrate may substantially the same outer frame shape as the circuit board.

With this configuration, the practical module in which the mounting component can be mounted on the first principal surface of the circuit board in a space inside the frame-shaped insulating substrate can be provided. The module is externally connected to another board or other element in the outer region of the circuit board where the connecting component is arranged. Thus the strength of connection between the module and another board when the module is externally connected to the other board can be improved.

The insulating substrate may include a plurality of insulating layers, the plurality of insulating layers may include respective end faces forming the contact surface, and the engagement structure may be formed by arranging the end faces of the insulating layers as being displaced from one another.

With this configuration, the arrangement in which the end faces of the insulating layers in the multilayer insulating substrate in the connecting component enables the engagement structure made of projections and depressions formed by the displaced end faces to be formed in the side surface of the connecting component.

In the contact surface, projections and depressions may be formed as the engagement structure in a thickness direction of the insulating substrate.

With this configuration, the projections and depressions are formed in the contact surface of the insulating substrate in contact with the resin layer in the thickness direction. Thus even if a stress or other force is exerted on the resin layer covering the side surface of the connecting component in a direction in which it separates from the first principal surface of the circuit board, movement of the resin layer in the direction in which it separates from the first principal surface of the circuit board can be reliably prevented by

engagement of the resin layer with the inner side surfaces of the depressions or the outer side surfaces of the projections formed in the side surface of the connecting component. Accordingly, the separation of the resin layer from the first principal surface of the circuit board can be reliably prevented. Even if a similar stress is exerted on the connecting component, for the same reason, the separation of the connecting component from the first principal surface of the circuit board can be reliably prevented.

According to preferred embodiments of the present invention, a method of manufacturing a module includes a preparing step of preparing a circuit board, a mounting step of mounting a mounting component and a connecting component for use in external connection on a first principal surface of the circuit board, and a molding step of forming a resin layer that covers the first principal surface of the circuit board, the mounting component, and a side surface of the connecting component. The connecting component includes an insulating substrate and a plurality of interlayer connection conductors arranged in the insulating substrate. Each of the interlayer connection conductors includes a first end connected to the first principal surface of the circuit board and a second end externally connected. An engagement structure for preventing the resin layer from being separated is formed in a contact surface of the insulating substrate with the resin layer.

With this method, the above-described module capable of reliably preventing separation of the resin layer or the connecting component from the first principal surface of the circuit board by the engagement structure formed in the contact surface of the insulating substrate in contact with the resin layer can be manufactured.

The engagement structure may be formed by cutting.

With this process, the engagement structure can be easily formed by cutting the contact surface of the insulating substrate in contact with the resin layer.

The insulating substrate may include a plurality of insulating layers. The engagement structure may be formed by arranging the end faces of the insulating layers as being displaced from one another.

With this process, the engagement structure made of the projections and depressions can be easily formed in the contact surface of the insulating substrate in contact with the resin layer by the arrangement in which the end faces of the insulating layers in the multilayer insulating substrate are displaced from one another.

Other features, elements, characteristics and advantages of the present invention will become more apparent from the following detailed description of preferred embodiments of the present invention with reference to the attached drawings.

#### BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS

FIG. 1 is a cross-sectional view of a module according to a first embodiment of the present invention;

FIG. 2 is an enlarged view of a main portion of the module illustrated in FIG. 1;

FIG. 3 illustrates an example method of manufacturing an engagement structure;

FIG. 4 illustrates a variation of the engagement structure;

FIG. 5 illustrates another variation of the engagement structure;

FIG. 6 illustrates yet another variation of the engagement structure;

FIG. 7 illustrates still another variation of the engagement structure;

FIGS. 8A1 to 8C2 illustrate a connecting component in a module according to a second embodiment of the present invention, FIGS. 8A1 and 8B1 are plan views of insulating layers in an insulating substrate, FIG. 8C1 is a plan view of the insulating substrate, and FIGS. 8A2 to 8C2 are cross-sectional views corresponding to FIGS. 8A1 to 8C1, respectively;

FIGS. 9A to 9C illustrate a variation of the connecting component, FIGS. 9A and 9B are plan views of the insulating layers in the insulating substrate, and FIG. 9C is a plan view of the insulating substrate;

FIGS. 10A to 10C illustrate another variation of the connecting component, FIGS. 10A and 10B are plan views of the insulating layers in the insulating substrate, and FIG. 10C is a plan view of the insulating substrate;

FIGS. 11A to 11C illustrate yet another variation of the connecting component, FIGS. 11A and 11B are plan views of the insulating layers in the insulating substrate, and FIG. 11C is a plan view of the insulating substrate;

FIGS. 12A and 12B illustrate a connecting component in a module according to a third embodiment of the present invention, FIG. 12A is a cross-sectional view of the insulating layers in the insulating substrate, and FIG. 12B is a cross-sectional view of the insulating substrate;

FIGS. 13A to 13C illustrate different variations of the connecting component; and

FIG. 14 is a cross-sectional view of a known module.

#### DETAILED DESCRIPTION OF THE INVENTION

##### First Embodiment

A first embodiment of the present invention is described with reference to FIGS. 1 to 3. FIG. 1 is a cross-sectional view of a module according to the first embodiment of the present invention. FIG. 2 is an enlarged view of a main portion of the module illustrated in FIG. 1. FIG. 3 illustrates an example method of manufacturing an engagement structure.

A module 1 is formed as a high-frequency communication module, such as a Bluetooth (registered trademark) module, a wireless local area network (LAN) module, or an antenna switch module, or a power supply circuit module by mounting the mounting components 3, such as ICs and stacked ceramic chip components 3, on both principal surfaces 2a and 2b of a circuit board 2 in the module 1. As illustrated in FIG. 1, the module 1 includes the circuit board 2, the mounting components 3 on both the principal surfaces 2a and 2b, and a connecting component 4 for use in external connection mounted on the first principal surface 2a.

A resin layer 5 covering the first principal surface 2a of the circuit board 2, the mounting components 3, and the inner side surface of the connecting component 4 is disposed on the first principal surface 2a of the circuit board 2. A resin layer 6 covering the second principal surface 2b and the mounting components 3 is disposed on the second principal surface 2b of the circuit board 2. Each of the resin layers 5 and 6 is made of general thermosetting resin for molding, such as epoxy resin or cyanate resin.

The circuit board 2 is made of a general substrate, such as a resin substrate made of glass epoxy resin or liquid crystal polymer, a low temperature co-fired ceramic (LTCC) substrate, or a glass substrate. Depending on the intended use of the module 1, the circuit board 2 may be a single-layer board

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or a multilayer board. A plurality of mounting electrodes **2c** for mounting the mounting components **3** and the connecting component **4** by bonding them using a binder, such as solder H, or ultrasonic vibration bonding are disposed on both the principal surfaces **2a** and **2b** of the circuit board **2**. Wiring electrodes, such as in-plane electrodes (not illustrated) and via conductors (not illustrated), made of conductive materials including silver, copper, gold, or other element are disposed inside the circuit board **2** as needed. The mounting electrodes **2c** are electrically connected through the wiring electrodes inside the circuit board **2**. Various electric circuits formed by combinations of the in-plane electrodes and via conductors may be disposed inside the circuit board **2**.

An example process of forming the circuit board **2** made of an LTCC multilayer substrate is described below. That is, first, ceramic green sheets are prepared. The ceramic green sheets are made of slurry sheets in which the mixed powder of aluminium oxide, glass, and other material is mixed with an organic binder, solvent, and other material. Then, via conductors for use in interlayer connection are formed by filling via holes formed by laser processing in predetermined positions of the ceramic green sheets with conductive paste including silver, copper, or other element and various wiring patterns are formed by printing using conductive paste. The ceramic green sheets are stacked and attached by pressure to form a ceramic laminate. The ceramic laminate is heated at low temperature in the neighborhood of approximately 1000° C., so-called, is low-temperature fired. In this way, the circuit board **2** is formed.

The connecting component **4** includes an insulating substrate **41** having substantially the same outer frame shape as the circuit board **2**. The insulating substrate **41** is made of a general substrate, such as a resin substrate made of glass epoxy resin or liquid crystal polymer, a low temperature co-fired ceramic (LTCC) substrate, or a glass substrate, as in the case of the circuit board **2**. The insulating substrate **41** may be a single-layer substrate or a multilayer substrate.

A plurality of interlayer connection conductors **43** are arranged in the insulating substrate **41** by providing conductive paste including silver, copper, gold, or other element or disposing metal bars, such as copper. Each of the interlayer connection conductors **43** includes a first end connected to the mounting electrode **2c** on the first principal surface **2a** of the circuit board **2** with the solder H or other element and a second end externally connected to another board or other element with the solder H or other element. This enables the module **1** (circuit board **2**) to be externally connected to the other board or element.

As illustrated in FIG. 2, which is an enlarged view of a region A surrounded by the dotted lines in FIG. 1, an engagement structure **45** for preventing the separation of the resin layer **5** is made of projections and depressions **44** extending in the thickness direction of the insulating substrate **41** over the whole of the frame-shaped inner side surfaces being a contact surface in contact with the resin layer **5**.

Next, an example method of manufacturing the module **1** is described.

First, the circuit board **2** is prepared (preparing step). After the mounting components **3** are mounted on the second principal surface **2b** of the circuit board **2**, the resin layer **6** is formed by filling the second principal surface **2b** with general thermosetting resin for molding, such as epoxy resin. Then, the mounting components **3** and the connecting component **4** are mounted on the first principal surface **2a** of the circuit board **2** (mounting step). The resin layer **5**

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covering the first principal surface **2a** of the circuit board **2**, the mounting components **3**, and the inner side surface of the connecting component **4** (insulating substrate **41**) is formed by filling the first principal surface **2a** of the circuit board **2** with resin, as in the case of the second principal surface **2b**, and the module **1** is completed (molding step). The process of mounting the mounting components **3**, the connecting component **4**, and the resin layer **5** on the first principal surface **2a** of the circuit board **2** and the process of mounting the mounting components **3** and the resin layer **6** on the second principal surface **2b** may be performed in any order.

As illustrated in FIG. 3, the projections and depressions **44** are formed as the engagement structure **45** in the inner side surface of the insulating substrate **41** in contact with the resin layer **5** by cutting with a cutting tool P. FIG. 3 illustrates only a part of the insulating substrate **41** for the sake of simplification of description. Similarly, FIGS. 4 to 7, which are used in the description below, also illustrate only a part of the insulating substrate **41**, and this note is not repeated in the description below.

(Variations of Engagement Structure)

Variations of the engagement structure **45** formed by cutting with the cutting tool P are described with reference to FIGS. 4 to 7. FIGS. 4 to 7 illustrate the variations of the engagement structure.

In the example illustrated in FIG. 4, a step **44a** is formed as the engagement structure **45** over the whole of the inner side surface of the insulating substrate **41** by cutting the inner side surface with the cutting tool P. The step **44a** is formed such that the lower portion of the inner side surface of the insulating substrate **41** protrudes toward the inside of the opening at a substantially central position of the insulating substrate **41** farther than the upper portion. With this configuration, for example, if the resin layer **5** attempts to move in a direction in which the resin layer **5** separates from the first principal surface **2a** of the circuit board **2**, the engagement of the resin layer **5** with the step **44a** prevents such a movement.

In the example illustrated in FIG. 5, a concave portion **44b** is formed as the engagement structure **45** over the whole of the inner side surface of the insulating substrate **41** by cutting the inner side surface with the cutting tool P. The concave portion **44b** has a substantially concave cross section. With this configuration, for example, if the resin layer **5** attempts to move in a direction in which the resin layer **5** separates from the first principal surface **2a** of the circuit board **2**, the engagement of the resin layer **5** with the concave portion **44b** prevents such a movement.

In the example illustrated in FIG. 6, an inclined slope **44c** is formed as the engagement structure **45** over the whole of the inner side surface of the insulating substrate **41** by cutting the inner side surface with the cutting tool P. The inclined slope **44c** has a substantially cup-shaped cross section that tapers toward the bottom. With this configuration, for example, if the resin layer **5** attempts to move in a direction in which the resin layer **5** separates from the first principal surface **2a** of the circuit board **2**, the engagement of the resin layer **5** with the inclined slope **44c** prevents such a movement.

In the example illustrated in FIG. 7, a groove **44d** is formed as the engagement structure **45** over the whole of the inner side surface of the insulating substrate **41** by cutting the inner side surface with the cutting tool P. With this configuration, for example, if the resin layer **5** attempts to move in a direction in which the resin layer **5** separates from

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the first principal surface **2a** of the circuit board **2**, the engagement of the resin layer **5** with the groove **44d** prevents such a movement.

As described above, according to the present embodiment, the mounting components **3** and the connecting component **4** for use in external connection are mounted on the first principal surface **2a** of the circuit board **2**. The resin layer **5** covering the first principal surface **2a** of the circuit board **2**, the mounting components **3**, and the side surface of the connecting component **4** is disposed on the first principal surface **2a** of the circuit board **2**. The interlayer connection conductors **43** are disposed in the insulating substrate **41** in the connecting component **4**. The first end of each of the interlayer connection conductors **43** is connected to the mounting electrode **2c** on the first principal surface **2a** of the circuit board **2**, and the second end thereof is externally connected. Thus the module **1** (circuit board **2**) is externally connected through the interlayer connection conductors **43**.

The engagement structure **45** for preventing the separation of the resin layer **5** is disposed in the contact surface of the insulating substrate **41** in the connecting component **4** in contact with the resin layer **5**. Accordingly, the engagement of the resin layer **5** with the engagement structure **45** formed in the contact surface of the insulating substrate **41** forming the side surface of the connecting component **4** in contact with the resin layer **5** can prevent the separation of the resin layer **5** or the connecting component **4** on the first principal surface **2a** of the circuit board **2**. Separation of the resin layer **5** from the side surface of the connecting component **4** can also be prevented. The degree of adhesion in the contact surface between the resin layer **5** and the connecting component **4** can be improved. Thus the module characteristics can be stabilized.

The module **1** having a practical configuration in which the mounting components **3** can be mounted on the first principal surface **2a** of the circuit board **2** in a space surrounded by the inner side surface of the frame-shaped insulating substrate **41** can be provided. The module **1** is externally connected to another board or other element in the outer region of the circuit board **2** where the connecting component **4** is arranged. Thus the strength of connection between the module **1** and another board when the module **1** is externally connected to the other board can be improved.

The projections and depressions **44** are formed in the contact surface of the insulating substrate **41** in contact with the resin layer **5** in the thickness direction. Thus even if a stress or other force is exerted on the resin layer **5** covering the side surface of the connecting component **4** in a direction in which it separates from the first principal surface **2a** of the circuit board **2**, the movement of the resin layer **5** in the direction in which it separates from the first principal surface **2a** of the circuit board **2** can be reliably prevented by the engagement of the resin layer **5** with the inner side surfaces of the depressions or the outer side surfaces of the projections formed in the side surface of the connecting component **4**. Accordingly, the separation of the resin layer **5** from the first principal surface **2a** of the circuit board **2** can be reliably prevented. Even if a similar stress is exerted on the connecting component **4**, for the same reason, the separation of the connecting component **4** from the first principal surface of the circuit board can be reliably prevented.

The connecting component **4** including the engagement structure **45** in the insulating substrate **41** can be formed in the contact surface in contact with the resin layer **5** on the first principal surface **2a** of the circuit board **2**. Thus the module **1** capable of reliably preventing separation of the

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resin layer **5** or the connecting component **4** from the first principal surface **2a** of the circuit board **2** can be easily manufactured.

The engagement structure **45** can be easily formed in the contact surface of the insulating substrate **41** in contact with the resin layer **5** by cutting using the cutting tool **P**.

## Second Embodiment

A second embodiment of the present invention is described with reference to FIGS. **8A1** to **8C2**. FIGS. **8A1** to **8C2** illustrate a connecting component in a module according to the second embodiment of the present invention. FIGS. **8A1** and **8B1** are plan views of insulating layers in an insulating substrate. FIG. **8C1** is a plan view of the insulating substrate. FIGS. **8A2** to **8C2** are cross-sectional views corresponding to FIGS. **8A1** to **8C1**, respectively.

A connecting component **104** in the second embodiment differs from the connecting component **4** in the first embodiment in that the engagement structure **45** is formed by the arrangement in which the inner side surfaces of a plurality of insulating layers **141a** and **141b** in an insulating substrate **141**, the inner side surfaces being in contact with the resin layer **5**, are displaced from each other, as illustrated in FIGS. **8A1** to **8C2**. The other configuration is substantially the same as that in the first embodiment, and the description of that configuration is omitted by using the same reference numerals.

In the present embodiment, the insulating substrate **141** is made of a multilayer ceramic substrate. The insulating substrate **141** is formed by stacking the insulating layers **141a** and **141b** with the plurality of interlayer connection conductors **43** formed in predetermined positions and firing the stacked layers. The insulating substrate **141** may be made of a multilayer resin substrate.

The insulating layers **141a** and **141b** have openings **146a** and **146b**, respectively, in their respective substantially central positions. The insulating layer **141a** is stacked on the insulating layer **141b**, and the insulating substrate **141** having a frame shape with an opening **146** in a substantially central position is formed. The opening **146a** in the insulating layer **141a**, which is stacked on the insulating layer **141b**, is slightly larger than the opening **146b**. Accordingly, when the insulating layer **141a** is stacked on the insulating layer **141b**, a step **144a** is formed as the engagement structure **45** over the whole of the inner side surface of the insulating substrate **141** (connecting component **104**) in contact with the resin layer **5**.

### (Variations of Connecting Component)

Variation of the engagement structure **45** formed by arrangement in which the inner side surfaces of the insulating layers **141a** and **141b** are displaced from each other are described with reference to FIGS. **9A** to **11C**. FIGS. **9A** to **11C** illustrate variations of the connecting component. FIGS. **9A**, **9B**, **10A**, **10B**, **11A**, and **11B** are plan views of the insulating layers in the insulating substrate. FIGS. **9C**, **10C**, and **11C** are plan views of the insulating substrate.

In the example illustrated in FIGS. **9A** to **9C**, the opening **146a** in the insulating layer **141a**, which is stacked on the insulating layer **141b**, has a substantially cross shape in which substantially rectangles overlap each other. Accordingly, when the insulating layer **141a** is stacked on the insulating layer **141b**, the steps **144a** are formed as the engagement structure **45** in the positions corresponding to the sides of the substantially rectangular opening **146b** in the insulating layer **141b** in the inner side surface of the insulating substrate **141** (connecting component **104**) in contact

with the resin layer 5. With this configuration, the engagement structure 45 has a shape more complicated than that in the second embodiment. Thus the degree of adhesion with the resin layer 5 can be further enhanced.

In the example illustrated in FIGS. 10A to 10C, the insulating layer 141a, which is stacked on the insulating layer 141b, has the opening 146a in which substantially semicircular holes are regularly arranged in the edge of the opening having substantially the same shape as the opening 146b in the insulating layer 141b. Accordingly, when the insulating layer 141a is stacked on the insulating layer 141b, the steps 144a are formed as the engagement structure 45 in the positions where the substantially semicircular holes in the opening 146a are formed in the inner side surface of the insulating substrate 141 (connecting component 104) in contact with the resin layer 5. With this configuration, the engagement structure 45 has a shape more complicated than that in the second embodiment. Thus the degree of adhesion with the resin layer 5 can be further enhanced.

In the example illustrated in FIGS. 11A to 11C, the insulating layers 141a and 141b have the substantially rectangular openings 146a and 146b, respectively. The orientation of the opening 146a and that of the opening 146b are different. Accordingly, when the insulating layer 141a is stacked on the insulating layer 141b, the steps 144a are formed as the engagement structure 45 in positions on both sides of the opening 146a in the longitudinal direction in the surface of the insulating layer 141a and in positions on both sides on both sides of the opening 146b in the longitudinal direction in the surface of the insulating layer 141b in the inner side surface of the insulating substrate 141 (connecting component 104) in contact with the resin layer 5. With this configuration, the engagement structure 45 has a shape more complicated than that in the second embodiment. Thus the degree of adhesion with the resin layer 5 can be further enhanced.

As described above, according to the present embodiment, substantially the same advantageous effects as in the first embodiment are obtainable. In addition, the advantageous effects described below are also obtainable. That is, the arrangement in which the inner side surfaces of the insulating layers 141a and 141b in the multilayer insulating substrate 141 in the connecting component 104 are displaced from each other enables the engagement structure 45 made of the steps 144a in the displaced inner side surfaces to be formed in the inner side surface of the connecting component 104. Accordingly, the arrangement in which the inner side surfaces of the insulating layers 141a and 141b in the multilayer insulating substrate 141 are displaced from each other enables the engagement structure 45 made of the steps 144a to be easily formed in the contact surface of the insulating substrate 141 in contact with the resin layer 5.

### Third Embodiment

A third embodiment of the present invention is described with reference to FIGS. 12A and 12B. FIGS. 12A and 12B illustrate a connecting component in a module according to a third embodiment of the present invention. FIG. 12A is a cross-sectional view of the insulating layers in the insulating substrate. FIG. 12B is a cross-sectional view of the insulating substrate.

A connecting component 204 in the third embodiment differs from the connecting component 104 in the second embodiment in that an insulating substrate 241 is formed by stacking six insulating layers 241a to 241f, as illustrated in FIGS. 12A and 12B. The engagement structure 45 is formed

by arrangement in which the inner side surfaces of the insulating layers 241a to 241f in the insulating substrate 241, the inner side surfaces being in contact with the resin layer 5, are displaced from one another. The other configuration is substantially the same as that in the above-described embodiments, and the description of that configuration is omitted by using the same reference numerals.

In the present embodiment, the insulating substrate 241 is made of a multilayer ceramic substrate. The insulating substrate 241 is formed by stacking the insulating layers 241a to 241f with the plurality of interlayer connection conductors 43 formed in predetermined positions and firing the stacked layers. The insulating substrate 241 may be made of a multilayer resin substrate.

The insulating layers 241a to 241f have openings 246a to 246f, respectively, in their respective substantially central positions. The insulating substrate 241 having a frame shape and an opening 246 in a substantially central position is formed by stacking the insulating layers 241a to 241f in sequence. The openings 246b, 246d, and 246f in the insulating layers 241b, 241d, and 241f are slightly larger than the openings 246a, 246c, and 246e in the insulating layers 241a, 241c, and 241e. Accordingly, when the insulating layers 241a to 241f are stacked in sequence, the large openings 246b, 246d, and 246f and the small openings 246a, 246c, and 246e are alternately arranged, and thus projections and depressions 244 are formed in the stacking direction as the engagement structure 45 over the whole of the inner side surface of the insulating substrate 241 (connecting component 204) in contact with the resin layer 5.

As described above, according to the present embodiment, even with the insulating substrate 241 formed by stacking three or more insulating layers, substantially the same advantageous effects as in the above-described embodiments are also obtainable.

### <Others>

In the above-described embodiments, the connecting components 4, 104, and 204 are made of the frame-shaped insulating substrates 41, 141, and 241, respectively. The shape of the insulating substrate included in the connecting component is not limited to the frame shape. Example variations of the connecting component with other than the frame shape are illustrated in FIGS. 13A and 13B.

In the example illustrated in FIG. 13A, a plurality of connecting components 304a made of strip-shaped insulating substrates 341a are arranged on the first principal surface 2a of the circuit board 2 in a substantially rectangular manner. In the example illustrated in FIG. 13B, a connecting component 304b made of a substantially rectangular insulating substrate 341b is arranged and mounted in a substantially central position on the first principal surface 2a of the circuit board 2.

When each of the insulating substrates 341a and 341b is made of a multilayer substrate, as in the case of the second and third embodiments, for example, the engagement structure 45 can be formed in a way described below. That is, the engagement structure 45 can be formed in the contact surface in contact with the resin layer 5 in each of the connecting components 304a and 304b by arrangement in which the end faces in the insulating layers included in the insulating substrates 341a and 341b in contact with the resin layer 5 are displaced from one another.

A plurality of connecting components of different types may be mounted on the first principal surface 2a of the circuit board 2. For example, as illustrated in the variation of the connecting component in FIG. 13C, the substantially rectangular connecting component 304b may be arranged

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inside a connecting component **304c** made of a frame-shaped insulating substrate **341c**.

The present invention is not limited to the above-described embodiments. In addition to the above-described ones, various changes may be made without departing from the spirit or scope of the present invention. For example, the opening in the frame-shaped insulating substrate may be changed to any shape, such as substantially rectangles or circles, depending on the configuration of the circuit board.

Any mounting components may be mounted on the circuit board so as to enable the module to have functions corresponding to the use achieved by an increase in the mounting density of the module. The mounting components may not be mounted on the second principal surface of the circuit board.

A method for mounting the mounting components on both principal surfaces of a circuit board in a module is not limited to a method using solder. For example, the mounting components may be mounted on the circuit board by a mounting method using an ultrasonic vibration technique, that using a surface activating technique by plasma, or a mounting method using bonding wires.

The present invention is widely applicable to modules each including a resin layer on a first principal surface of a circuit board.

While preferred embodiments of the invention have been described above, it is to be understood that variations and modifications will be apparent to those skilled in the art without departing from the scope and spirit of the invention. The scope of the invention, therefore, is to be determined solely by the following claims.

What is claimed is:

1. A module comprising:  
a circuit board;  
a mounting component mounted on a first principal surface of the circuit board;  
a connecting component for use in external connection mounted on the first principal surface of the circuit board; and  
a resin layer that covers the first principal surface of the circuit board, the mounting component, and a side surface of the connecting component,  
the connecting component including:  
an insulating substrate; and  
a plurality of interlayer connection conductors arranged in the insulating substrate,  
wherein each of the interlayer connection conductors includes a first end connected to the first principal surface of the circuit board and a second end externally connected, and  
the insulating substrate has a frame shape with frame-shaped inner side surfaces, covers the plurality of interlayer connection conductors, and includes an engagement structure for preventing the resin layer from being separated, and wherein the engagement structure is formed in each of the frame-shaped inner side surfaces of the insulating substrate being in contact with the resin layer.
2. The module according to claim 1, wherein the insulating substrate has substantially the same outer frame shape as the circuit board.
3. The module according to claim 1, wherein the insulating substrate includes a plurality of insulating layers, the plurality of insulating layers include respective end faces forming the contact surface, and

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the engagement structure is formed by arranging the end faces of the insulating layers as being displaced from one another.

4. The module according to claim 1, wherein projections and depressions are formed as the engagement structure in the contact surface in a thickness direction of the insulating substrate.

5. A method of manufacturing a module, the method comprising:

- a preparing step of preparing a circuit board;
- a mounting step of mounting a mounting component and a connecting component for use in external connection on a first principal surface of the circuit board; and
- a molding step of forming a resin layer that covers the first principal surface of the circuit board, the mounting component, and a side surface of the connecting component,

the connecting component including:

- an insulating substrate; and
- a plurality of interlayer connection conductors arranged in the insulating substrate,

wherein each of the interlayer connection conductors includes a first end connected to the first principal surface of the circuit board and a second end externally connected, and

the insulating substrate has a frame shape with frame-shaped inner side surfaces, covers the plurality of interlayer connection conductors, and includes an engagement structure for preventing the resin layer from being separated, and wherein the engagement structure is formed in each of the frame-shaped inner side surfaces of the insulating substrate being in contact with the resin layer.

6. The method of manufacturing a module according to claim 5, wherein the engagement structure is formed by cutting.

7. The method of manufacturing a module according to claim 5, wherein the insulating substrate includes a plurality of insulating layers, and

the engagement structure is formed by arranging end faces of the insulating layers as being displaced from one another.

8. The module according to claim 2, wherein the insulating substrate includes a plurality of insulating layers, the plurality of insulating layers include respective end faces forming the contact surface, and the engagement structure is formed by arranging the end faces of the insulating layers as being displaced from one another.

9. The module according to claim 2, wherein projections and depressions are formed as the engagement structure in the contact surface in a thickness direction of the insulating substrate.

10. The module according to claim 3, wherein projections and depressions are formed as the engagement structure in the contact surface in a thickness direction of the insulating substrate.

11. The module according to claim 1, wherein the first principal surface is a bottom surface of the circuit board and the engagement structure is located at a side of the bottom surface of the circuit board.

12. The method of manufacturing a module according to claim 5, wherein the first principal surface is a bottom surface of the circuit board and the engagement structure is located at a side of the bottom surface of the circuit board.

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